

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent  $CdV/dt$  effect decline
- ★ Advanced high cell density Trench technology

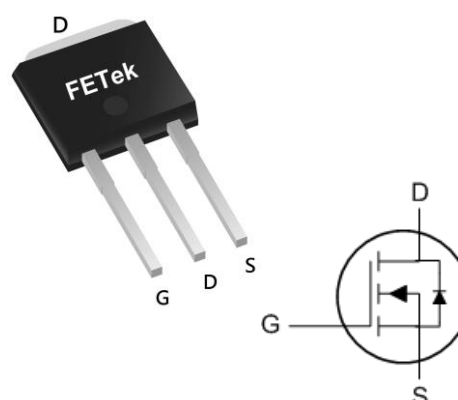
**Product Summary**


| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 30V   | 5.5mΩ | 80A |

**Description**

The FKR3006 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FKR3006 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**TO251 Pin Configuration**

**Absolute Maximum Ratings**

| Symbol                | Parameter                                  | Rating     | Units      |
|-----------------------|--------------------------------------------|------------|------------|
| $V_{DS}$              | Drain-Source Voltage                       | 30         | V          |
| $V_{GS}$              | Gate-Source Voltage                        | $\pm 20$   | V          |
| $I_D@T_C=25^\circ C$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 80         | A          |
| $I_D@T_C=100^\circ C$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 57         | A          |
| $I_D@T_A=25^\circ C$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 17         | A          |
| $I_D@T_A=70^\circ C$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 14.5       | A          |
| $I_{DM}$              | Pulsed Drain Current <sup>2</sup>          | 160        | A          |
| EAS                   | Single Pulse Avalanche Energy <sup>3</sup> | 115        | mJ         |
| $I_{AS}$              | Avalanche Current                          | 48         | A          |
| $P_D@T_C=25^\circ C$  | Total Power Dissipation <sup>4</sup>       | 53         | W          |
| $P_D@T_A=25^\circ C$  | Total Power Dissipation <sup>4</sup>       | 2.4        | W          |
| $T_{STG}$             | Storage Temperature Range                  | -55 to 175 | $^\circ C$ |
| $T_J$                 | Operating Junction Temperature Range       | -55 to 175 | $^\circ C$ |

**Thermal Data**

| Symbol          | Parameter                                                       | Typ. | Max. | Unit         |
|-----------------|-----------------------------------------------------------------|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-ambient (Steady State) <sup>1</sup> | ---  | 62   | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>                   | ---  | 2.8  | $^\circ C/W$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol                       | Parameter                                      | Conditions                                                | Min. | Typ.  | Max.      | Unit                |
|------------------------------|------------------------------------------------|-----------------------------------------------------------|------|-------|-----------|---------------------|
| $BV_{DSS}$                   | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                              | 30   | ---   | ---       | V                   |
| $\Delta BV_{DSS}/\Delta T_J$ | BVDSS Temperature Coefficient                  | Reference to $25^\circ\text{C}$ , $I_D=1mA$               | ---  | 0.028 | ---       | $V/^\circ\text{C}$  |
| $R_{DS(ON)}$                 | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=30A$                                  | ---  | ---   | 5.5       | $m\Omega$           |
|                              |                                                | $V_{GS}=4.5V$ , $I_D=15A$                                 | ---  | ---   | 9         |                     |
| $V_{GS(th)}$                 | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                          | 1.0  | ---   | 2.5       | V                   |
| $\Delta V_{GS(th)}$          | $V_{GS(th)}$ Temperature Coefficient           |                                                           | ---  | -6.16 | ---       | $mV/^\circ\text{C}$ |
| $I_{DSS}$                    | Drain-Source Leakage Current                   | $V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$       | ---  | ---   | 1         | $\mu A$             |
|                              |                                                | $V_{DS}=24V$ , $V_{GS}=0V$ , $T_J=55^\circ\text{C}$       | ---  | ---   | 5         |                     |
| $I_{GSS}$                    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                            | ---  | ---   | $\pm 100$ | nA                  |
| $g_{fs}$                     | Forward Transconductance                       | $V_{DS}=5V$ , $I_D=30A$                                   | ---  | 22    | ---       | S                   |
| $R_g$                        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1MHz$                      | ---  | 1.7   | 3.4       | $\Omega$            |
| $Q_g$                        | Total Gate Charge (4.5V)                       | $V_{DS}=20V$ , $V_{GS}=4.5V$ , $I_D=12A$                  | ---  | 20.8  | ---       | nC                  |
| $Q_{gs}$                     | Gate-Source Charge                             |                                                           | ---  | 5.3   | ---       |                     |
| $Q_{gd}$                     | Gate-Drain Charge                              |                                                           | ---  | 10.5  | ---       |                     |
| $T_{d(on)}$                  | Turn-On Delay Time                             | $V_{DD}=12V$ , $V_{GS}=10V$ , $R_G=3.3\Omega$<br>$I_D=5A$ | ---  | 9     | ---       | ns                  |
| $T_r$                        | Rise Time                                      |                                                           | ---  | 21.6  | ---       |                     |
| $T_{d(off)}$                 | Turn-Off Delay Time                            |                                                           | ---  | 26.6  | ---       |                     |
| $T_f$                        | Fall Time                                      |                                                           | ---  | 10.5  | ---       |                     |
| $C_{iss}$                    | Input Capacitance                              | $V_{DS}=15V$ , $V_{GS}=0V$ , $f=1MHz$                     | ---  | 2295  | ---       | pF                  |
| $C_{oss}$                    | Output Capacitance                             |                                                           | ---  | 267   | ---       |                     |
| $C_{rss}$                    | Reverse Transfer Capacitance                   |                                                           | ---  | 210   | ---       |                     |

**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                      | Min. | Typ. | Max. | Unit |
|----------|------------------------------------------|-------------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,5</sup> | $V_G=V_D=0V$ , Force Current                    | ---  | ---  | 80   | A    |
| $I_{SM}$ | Pulsed Source Current <sup>2,5</sup>     |                                                 | ---  | ---  | 160  | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ\text{C}$ | ---  | ---  | 1    | V    |

Note :

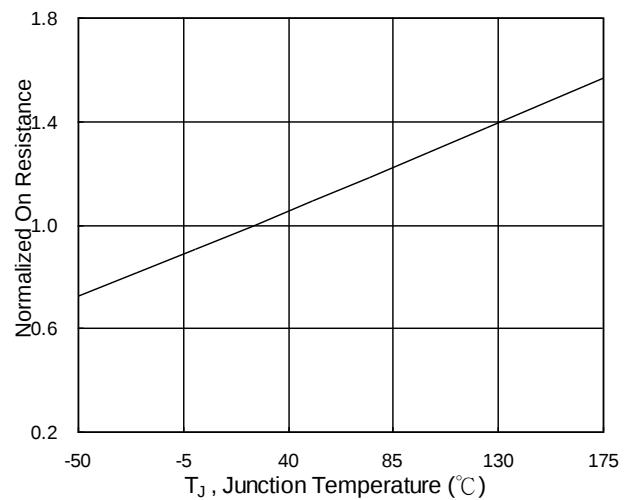
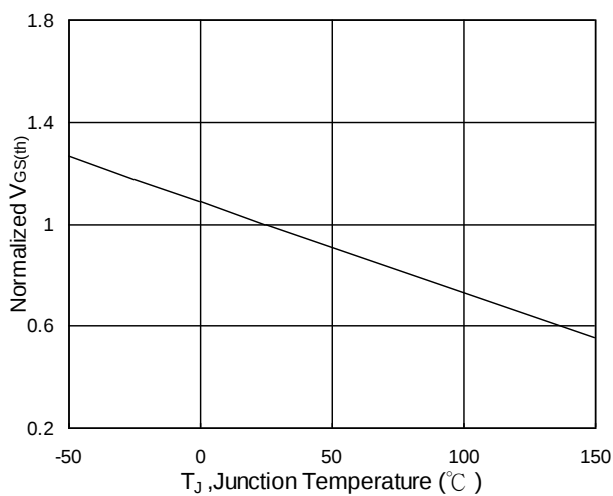
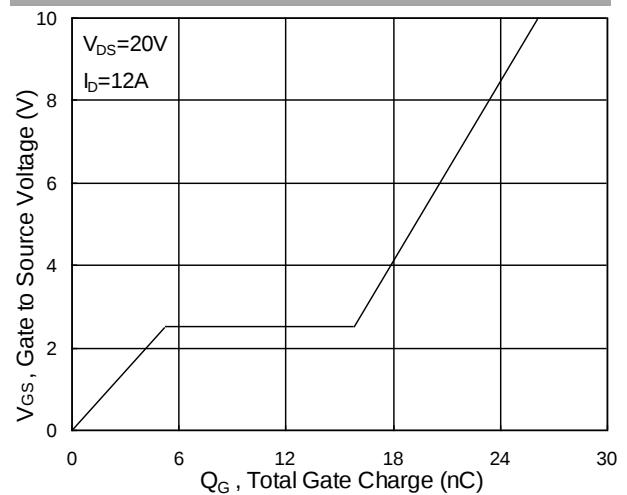
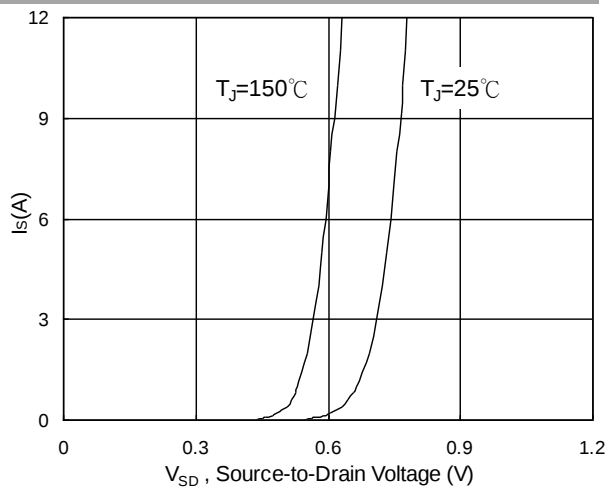
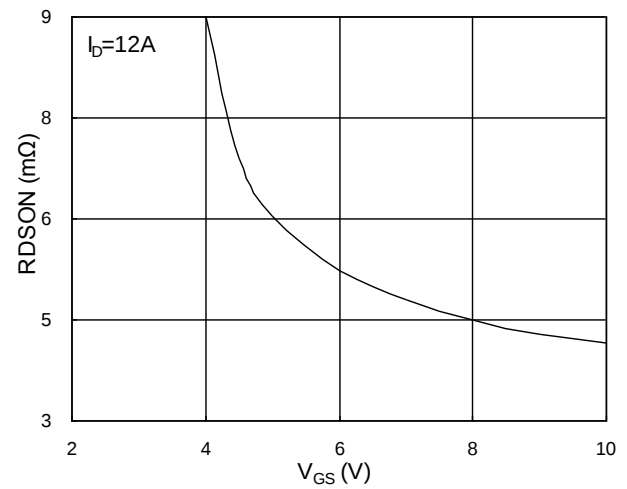
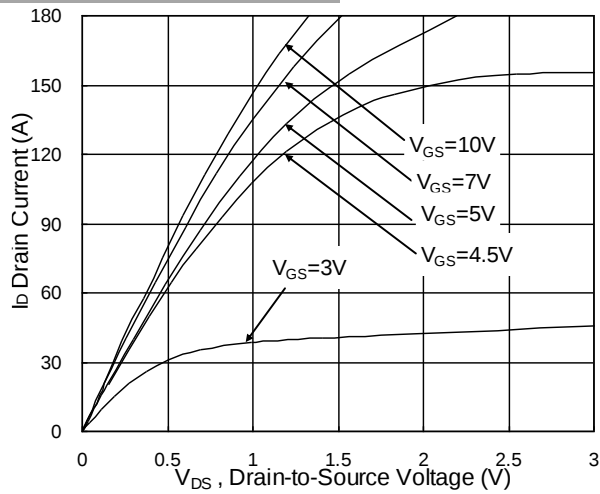
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.

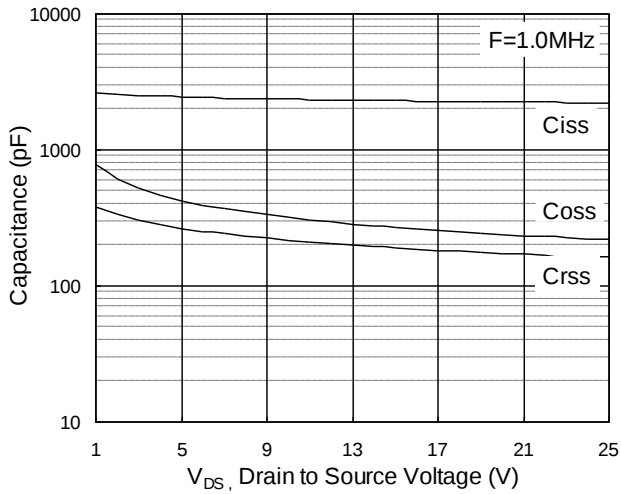
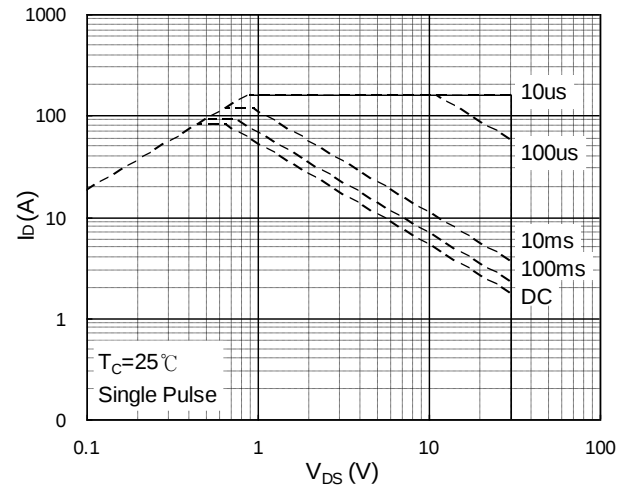
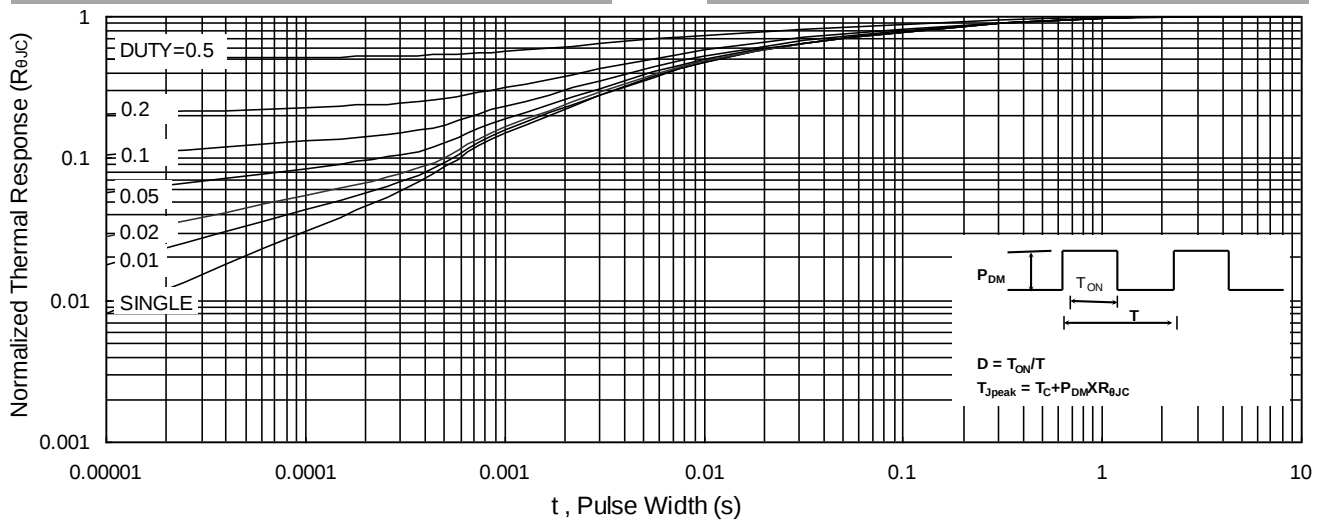
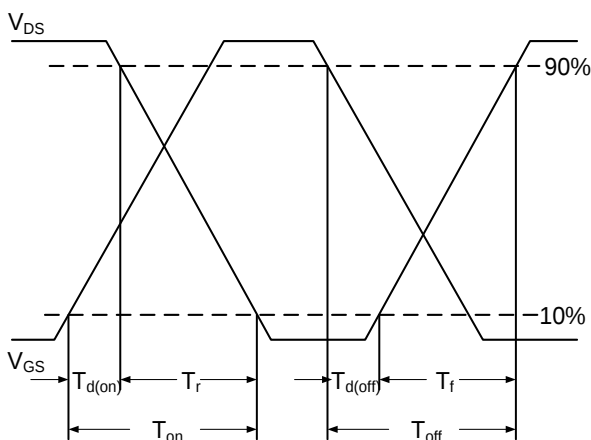
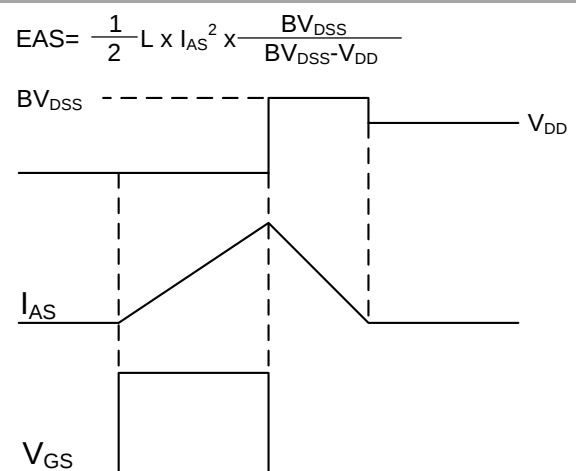
2. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ 

3. The EAS data shows Max. rating. The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=48A$ 

4. The power dissipation is limited by  $175^\circ\text{C}$  junction temperature

5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

**Typical Characteristics**



**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**